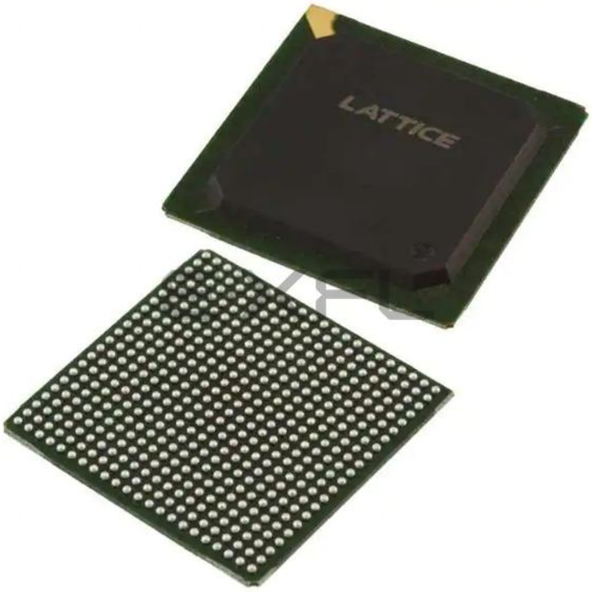

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

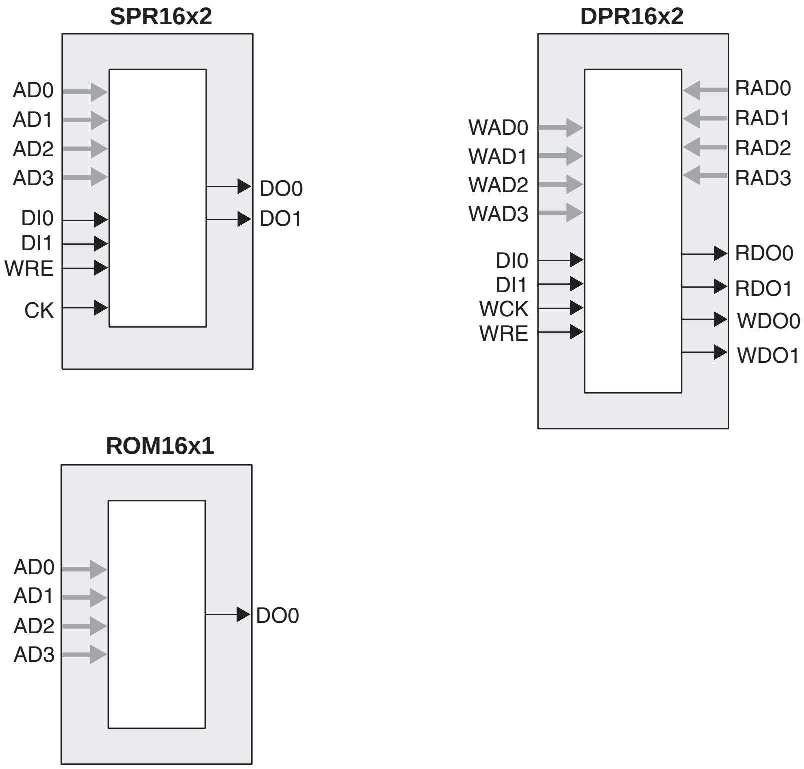
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	6100
Total RAM Bits	94208
Number of I/O	224
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfec6e-3fn484c

Figure 2-5. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

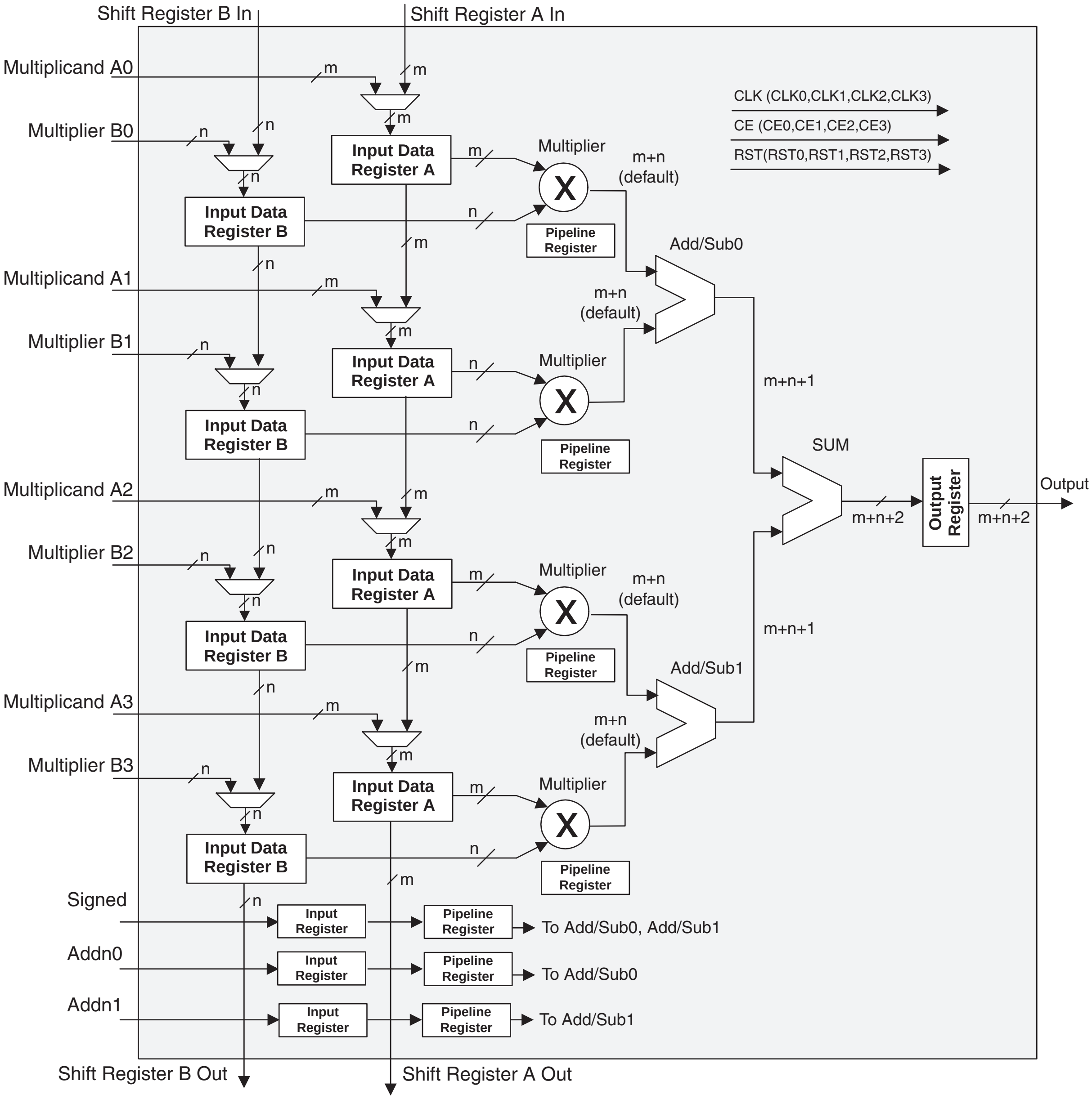
Logic	Ripple	RAM[1]	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x 2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

1. These modes are not available in PFF blocks

MULTADDSUM sysDSP Element

In this case, the operands A0 and B0 are multiplied and the result is added/subtracted with the result of the multiplier operation of operands A1 and B1. Additionally the operands A2 and B2 are multiplied and the result is added/subtracted with the result of the multiplier operation of operands A3 and B3. The result of both addition/subtraction are added in a summation block. The user can enable the input, output and pipeline registers. Figure 2-22 shows the MULTADDSUM sysDSP element.

Figure 2-22. MULTADDSUM



Clock, Clock Enable and Reset Resources

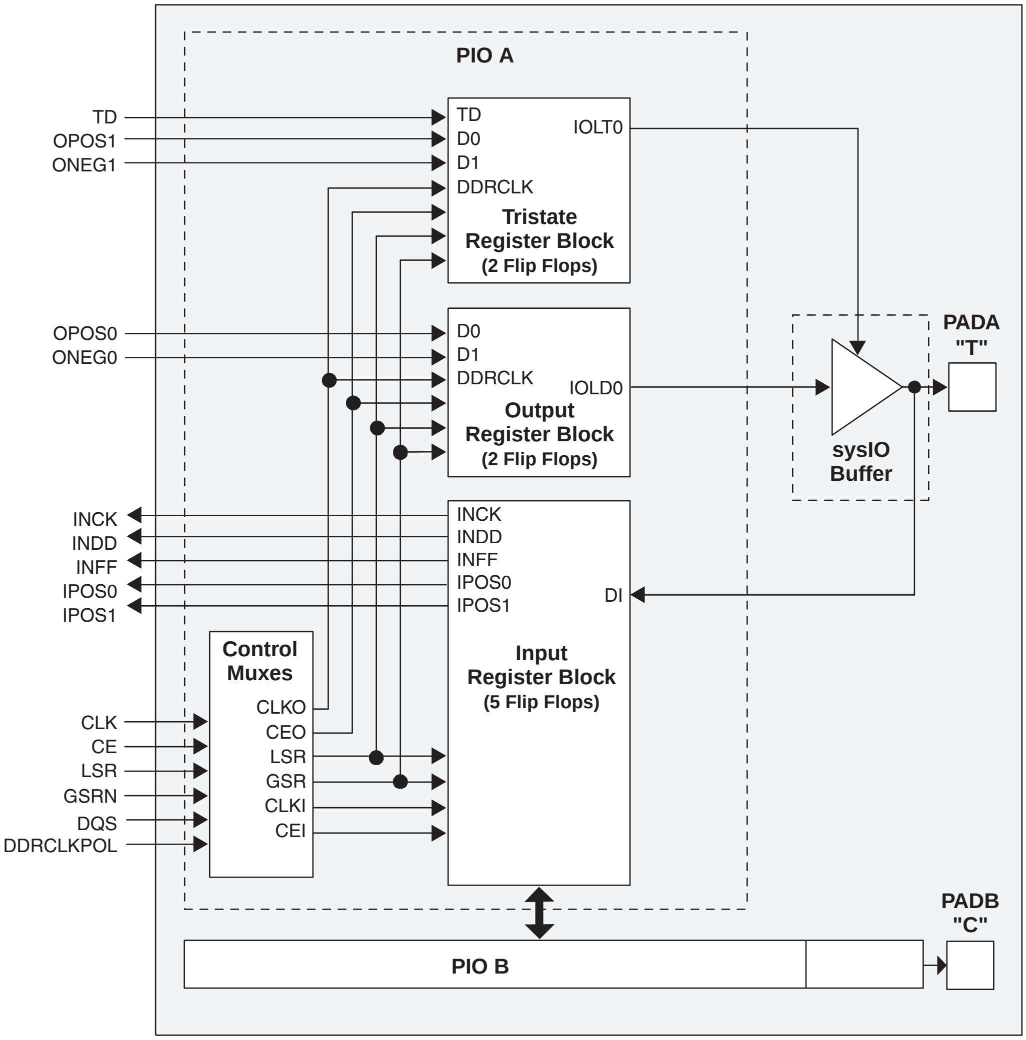
Global Clock, Clock Enable and Reset signals from routing are available to every DSP block. Four Clock, Reset and Clock Enable signals are selected for the sysDSP block. From four clock sources (CLK0, CLK1, CLK2, CLK3) one clock is selected for each input register, pipeline register and output register. Similarly Clock enable (CE) and Reset (RST) are selected from their four respective sources (CE0, CE1, CE2, CE3 and RST0, RST1, RST2, RST3) at each input register, pipeline register and output register.

For further information about the sysDSP block, please see the list of technical information at the end of this data sheet.

Programmable I/O Cells (PIC)

Each PIC contains two PIOs connected to their respective sysI/O Buffers which are then connected to the PADs as shown in Figure 2-24. The PIO Block supplies the output data (DO) and the Tri-state control signal (TO) to sysI/O buffer, and receives input from the buffer.

Figure 2-24. PIC Diagram



Two adjacent PIOs can be joined to provide a differential I/O pair (labeled as “T” and “C”) as shown in Figure 2-25. The PAD Labels “T” and “C” distinguish the two PIOs. Only the PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs.

One of every 16 PIOs contains a delay element to facilitate the generation of DQS signals. The DQS signal feeds the DQS bus which spans the set of 16 PIOs. Figure 2-25 shows the assignment of DQS pins in each set of 16 PIOs. The exact DQS pins are shown in a dual function in the Logic Signal Connections table at the end of this data sheet. Additional detail is provided in the Signal Descriptions table at the end of this data sheet. The DQS signal from the bus is used to strobe the DDR data from the memory into input register blocks. This interface is designed for memories that support one DQS strobe per eight bits of data.

Input Register Block

The input register block contains delay elements and registers that can be used to condition signals before they are passed to the device core. Figure 2-26 shows the diagram of the input register block.

Input signals are fed from the sysI/O buffer to the input register block (as signal DI). If desired the input signal can bypass the register and delay elements and be used directly as a combinatorial signal (INDD), a clock (INCK) and in selected blocks the input to the DQS delay block. If one of the bypass options is not chosen, the signal first passes through an optional delay block. This delay, if selected, reduces input-register hold-time requirement when using a global clock.

The input block allows two modes of operation. In the single data rate (SDR) the data is registered, by one of the registers in the single data rate sync register block, with the system clock. In the DDR Mode two registers are used to sample the data on the positive and negative edges of the DQS signal creating two data streams, D0 and D2. These two data streams are synchronized with the system clock before entering the core. Further discussion on this topic is in the DDR Memory section of this data sheet.

Figure 2-27 shows the input register waveforms for DDR operation and Figure 2-28 shows the design tool primitives. The SDR/SYNC registers have reset and clock enable available.

The signal DDRCLKPOL controls the polarity of the clock used in the synchronization registers. It ensures adequate timing when data is transferred from the DQS to system clock domain. For further discussion on this topic, see the DDR Memory section of this data sheet.

Figure 2-26. Input Register Diagram

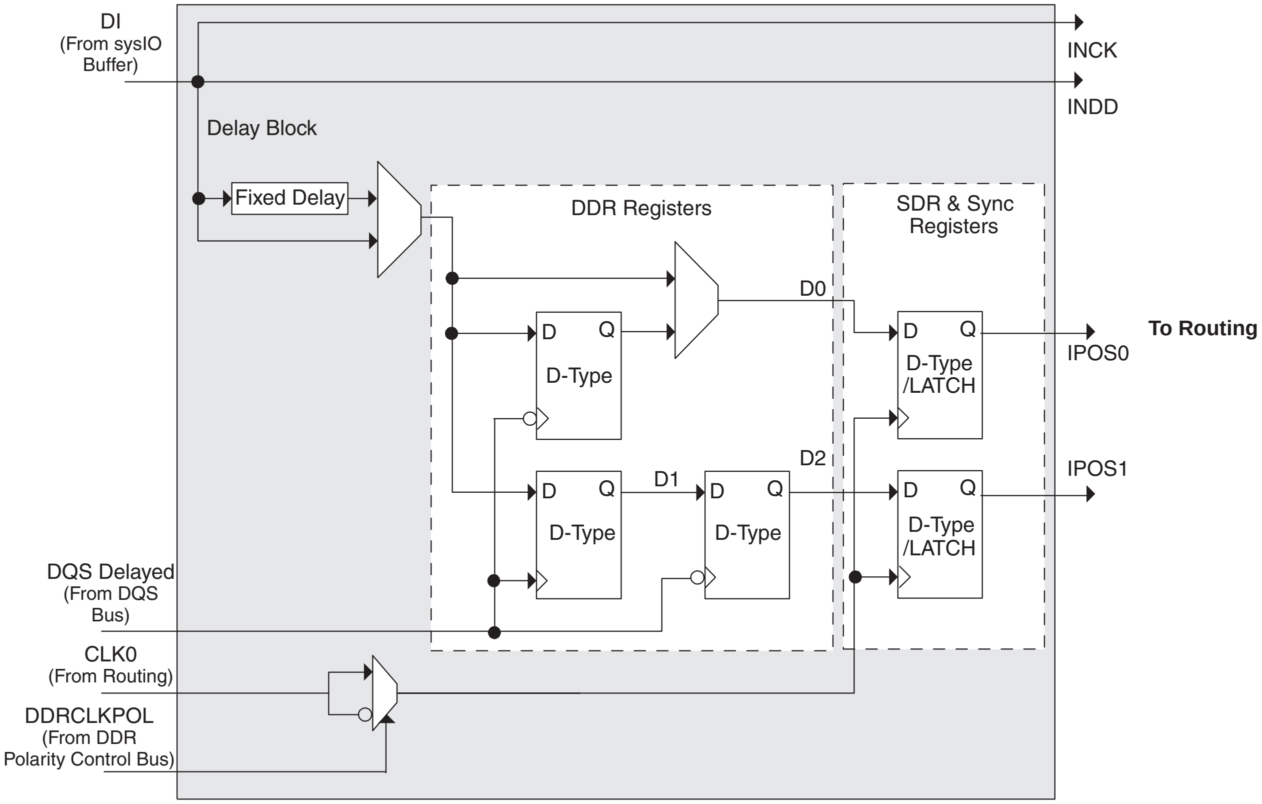
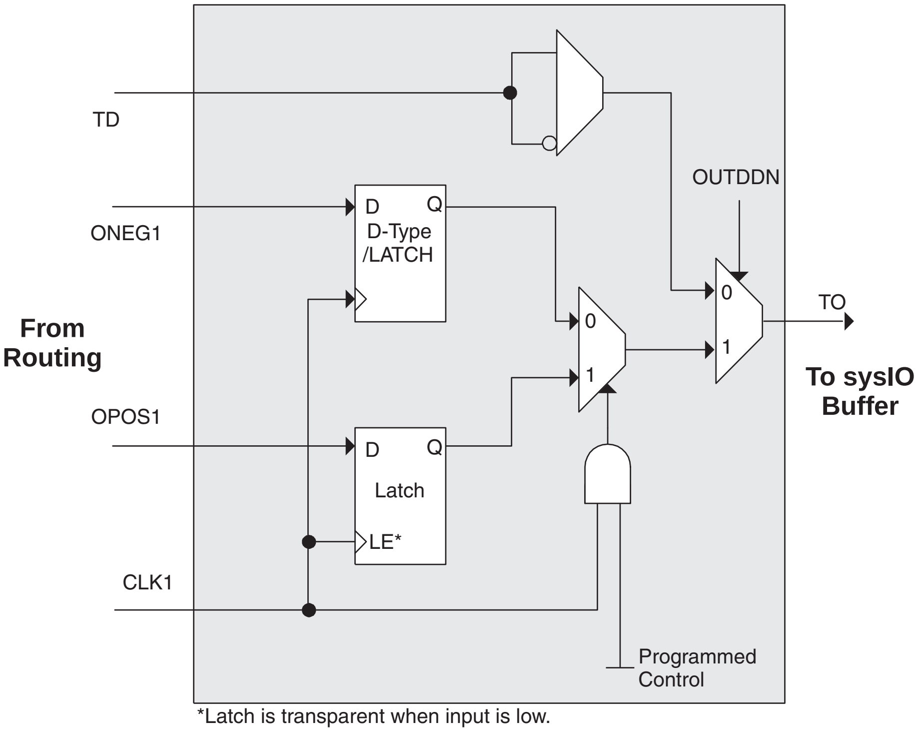


Figure 2-31. Tristate Register Block



Control Logic Block

The control logic block allows the selection and modification of control signals for use in the PIO block. A clock is selected from one of the clock signals provided from the general purpose routing and a DQS signal provided from the programmable DQS pin. The clock can optionally be inverted.

The clock enable and local reset signals are selected from the routing and optionally inverted. The global tristate signal is passed through this block.

DDR Memory Support

Implementing high performance DDR memory interfaces requires dedicated DDR register structures in the input (for read operations) and in the output (for write operations). As indicated in the PIO Logic section, the LatticeEC devices provide this capability. In addition to these registers, the LatticeEC devices contain two elements to simplify the design of input structures for read operations: the DQS delay block and polarity control logic.

DLL Calibrated DQS Delay Block

Source Synchronous interfaces generally require the input clock to be adjusted in order to correctly capture data at the input register. For most interfaces a PLL is used for this adjustment. However in DDR memories the clock (referred to as DQS) is not free running so this approach cannot be used. The DQS Delay block provides the required clock alignment for DDR memory interfaces.

The DQS signal (selected PIOs only) feeds from the PAD through a DQS delay element to a dedicated DQS routing resource. The DQS signal also feeds polarity control logic, which controls the polarity of the clock to the sync registers in the input register blocks. Figures 2-32 and 2-33 show how the DQS transition signals are routed to the PIOs.

The temperature, voltage and process variations of the DQS delay block are compensated by a set of calibration (6-bit bus) signals from two DLLs on opposite sides of the device. Each DLL compensates DQS Delays in its half of the device as shown in Figure 2-33. The DLL loop is compensated for temperature, voltage and process variations by the system clock and feedback loop.

be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS3.3, 2.5, 1.8, 1.5 and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Device Configuration

All LatticeECP/EC devices contain two possible ports that can be used for device configuration. The test access port (TAP), which supports bit-wide configuration, and the sysCONFIG port that supports both byte-wide and serial configuration.

The TAP supports both the IEEE Std. 1149.1 Boundary Scan specification and the IEEE Std. 1532 In-System Configuration specification. The sysCONFIG port is a 20-pin interface with six of the I/Os used as dedicated pins and the rest being dual-use pins (please refer to TN1053 for more information about using the dual-use pins as general purpose I/O). There are four configuration options for LatticeECP/EC devices:

1. Industry standard SPI memories.
2. Industry standard byte wide flash and ispMACH 4000 for control/addressing.
3. Configuration from system microprocessor via the configuration bus or TAP.
4. Industry standard FPGA board memory.

On power-up, the FPGA SRAM is ready to be configured with the sysCONFIG port active. The IEEE 1149.1 serial mode can be activated any time after power-up by sending the appropriate command through the TAP port. Once a configuration port is selected, that port is locked and another configuration port cannot be activated until the next power-up sequence.

For more information about device configuration, please see the list of technical documentation at the end of this data sheet.

Internal Logic Analyzer Capability (ispTRACY)

All LatticeECP/EC devices support an internal logic analyzer diagnostic feature. The diagnostic features provide capabilities similar to an external logic analyzer, such as programmable event and trigger condition and deep trace memory. This feature is enabled by Lattice's ispTRACY. The ispTRACY utility is added into the user design at compile time.

For more information about ispTRACY, please see information regarding additional technical documentation at the end of this data sheet.

External Resistor

LatticeECP/EC devices require a single external, 10K ohm +/- 1% value between the XRES pin and ground. Device configuration will not be completed if this resistor is missing. There is no boundary scan register on the external resistor pad.

Supply Current (Standby)[1, 2, 3, 4]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[5]	Units
I_{CC}	Core Power Supply Current	LFEC1	6	mA
		LFEC3	10	mA
		LFECP6/LFEC6	15	mA
		LFECP10/LFEC10	25	mA
		LFECP15/LFEC15	35	mA
		LFECP20/LFEC20	60	mA
		LFECP33/LFEC33	85	mA
I_{CCAUX}	Auxiliary Power Supply Current		15	mA
I_{CCPLL}	PLL Power Supply Current		5	mA
I_{CCIO}	Bank Power Supply Current[6]		2	mA
I_{CCJ}	V_{CCJ} Power Supply Current		5	mA

1. For further information about supply current, please see the list of technical documentation at the end of this data sheet.
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V_{CCIO} or GND.
3. Frequency 0MHz.
4. Pattern represents a “blank” configuration data file.
5. T_J=25°C, power supplies at nominal voltage.
6. Per bank.

sysI/O Single-Ended DC Electrical Characteristics

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL}[1] (mA)	I_{OH}[1] (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVTTL	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.8	-0.3	0.35V_{CCIO}	0.65V_{CCIO}	3.6	0.4	V_{CCIO} - 0.4	16, 12, 8, 4	-16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.5	-0.3	0.35V_{CCIO}	0.65V_{CCIO}	3.6	0.4	V_{CCIO} - 0.4	8, 4	-8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2	-0.3	0.35V_{CC}	0.65V_{CC}	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
PCI	-0.3	0.3V_{CCIO}	0.5V_{CCIO}	3.6	0.1V_{CCIO}	0.9V_{CCIO}	1.5	-0.5
SSTL3 class I	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.7	V_{CCIO} - 1.1	8	-8
SSTL3 class II	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.5	V_{CCIO} - 0.9	16	-16
SSTL2 class I	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.54	V_{CCIO} - 0.62	7.6	-7.6
SSTL2 class II	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.35	V_{CCIO} - 0.43	15.2	-15.2
SSTL18 class I	-0.3	V_{REF} - 0.125	V_{REF} + 0.125	3.6	0.4	V_{CCIO} - 0.4	6.7	-6.7
HSTL15 class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	8	-8
HSTL15 class III	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	24	-8
HSTL18 class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	9.6	-9.6
HSTL18 class II	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	16	-16
HSTL18 class III	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	24	-8

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O bank and the end of an I/O bank, as shown in the logic signal connections table shall not exceed n * 8mA. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

sysI/O Differential Electrical Characteristics

LVDS

Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input voltage		0	—	2.4	V
V_{THD}	Differential input threshold		+/-100	—	—	mV
V_{CM}	Input common mode voltage	100mV ð V_{THD}	$V_{THD}/2$	1.2	1.8	V
		200mV ð V_{THD}	$V_{THD}/2$	1.2	1.9	V
		350mV ð V_{THD}	$V_{THD}/2$	1.2	2.0	V
I_{IN}	Input current	Power on or power off	—	—	+/-10	µA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	R_T = 100 Ohm	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	R_T = 100 Ohm	0.9V	1.03	—	V
V_{OD}	Output voltage differential	(V_{OP} - V_{OM}), R_T = 100 Ohm	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	(V_{OP} + V_{OM})/2, R_T = 100 Ohm	1.125	1.25	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{OSD}	Output short circuit current	V_{OD} = 0V Driver outputs shorted	—	—	6	mA

LFEC1, LFEC3 Logic Signal Connections: 208 PQFP (Cont.)

	LFEC1				LFEC3			
Pin Number	Pin Function	Bank	LVDS	Dual Function	Pin Function	Bank	LVDS	Dual Function
85	VCCIO4	4			VCCIO4	4		
86	PB10A	4	T	WRITEN	PB18A	4	T	WRITEN
87	PB10B	4	C	CS1N	PB18B	4	C	CS1N
88	PB11A	4	T	VREF1_4	PB19A	4	T	VREF1_4
89	PB11B	4	C	CSN	PB19B	4	C	CSN
90	PB12A	4	T	VREF2_4	PB20A	4	T	VREF2_4
91	PB12B	4	C	D0/SPID7	PB20B	4	C	D0/SPID7
92	PB13A	4	T	D2/SPID5	PB21A	4	T	D2/SPID5
93	GND4	4			GND4	4		
94	PB13B	4	C	D1/SPID6	PB21B	4	C	D1/SPID6
95	PB14A	4	T	BDQS14	PB22A	4	T	BDQS22
96	PB14B	4	C	D3/SPID4	PB22B	4	C	D3/SPID4
97	PB15A	4	T		PB23A	4	T	
98	PB15B	4	C	D4/SPID3	PB23B	4	C	D4/SPID3
99	PB16A	4	T		PB24A	4	T	
100	PB16B	4	C	D5/SPID2	PB24B	4	C	D5/SPID2
101	PB17A	4	T		PB25A	4	T	
102	PB17B	4	C	D6/SPID1	PB25B	4	C	D6/SPID1
103	NC	-			NC	-		
104	VCCIO4	4			VCCIO4	4		
105*	GND3 GND4	-			GND3 GND4	-		
106	VCCIO3	3			VCCIO3	3		
107	PR14B	3	C	VREF2_3	PR18B	3	C	VREF2_3
108	PR14A	3	T	VREF1_3	PR18A	3	T	VREF1_3
109	PR13B	3	C		PR17B	3	C	
110	PR13A	3	T		PR17A	3	T	
111	PR12B	3	C		PR16B	3	C	
112	PR12A	3	T		PR16A	3	T	
113	PR11B	3	C		PR15B	3	C	
114	PR11A	3	T	RDQS11	PR15A	3	T	RDQS15
115	PR10B	3	C	RLM0_PLLC_FB_A	PR14B	3	C	RLM0_PLLC_FB_A
116	GND3	3			GND3	3		
117	PR10A	3	T	RLM0_PLLT_FB_A	PR14A	3	T	RLM0_PLLT_FB_A
118	PR9B	3	C	RLM0_PLLC_IN_A	PR13B	3	C	RLM0_PLLC_IN_A
119	PR9A	3	T	RLM0_PLLT_IN_A	PR13A	3	T	RLM0_PLLT_IN_A
120	VCCIO3	3			VCCIO3	3		
121	PR8B	3	C	DI/CSSPIN	PR12B	3	C	DI/CSSPIN
122	PR8A	3	T	DOUT/CSON	PR12A	3	T	DOUT/CSON
123	PR7B	3	C	BUSY/SISPI	PR11B	3	C	BUSY/SISPI
124	PR7A	3	T	D7/SPID0	PR11A	3	T	D7/SPID0
125	CFG2	3			CFG2	3		
126	CFG1	3			CFG1	3		

LFEC3 and LFECP/EC6 Logic Signal Connections: 256 fpBGA

Ball Number	LFEC3				LFECP6/LFEC6			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
GND	GND7	7			GND7	7		
D4	PL2A	7	T	VREF2_7	PL2A	7	T	VREF2_7
D3	PL2B	7	C	VREF1_7	PL2B	7	C	VREF1_7
C3	PL3A	7	T		PL3A	7	T	
C2	PL3B	7	C		PL3B	7	C	
B1	PL4A	7	T		PL4A	7	T	
C1	PL4B	7	C		PL4B	7	C	
E3	PL5A	7	T		PL5A	7	T	
E4	PL5B	7	C		PL5B	7	C	
F4	PL6A	7	T	LDQS6	PL6A	7	T	LDQS6
F5	PL6B	7	C		PL6B	7	C	
G4	PL7A	7	T		PL7A	7	T	
G3	PL7B	7	C		PL7B	7	C	
D2	PL8A	7	T		PL8A	7	T	
D1	PL8B	7	C		PL8B	7	C	
E1	PL9A	7	T	PCLKT7_0	PL9A	7	T	PCLKT7_0
GND	GND7	7			GND7	7		
E2	PL9B	7	C	PCLKC7_0	PL9B	7	C	PCLKC7_0
F3	XRES	6			XRES	6		
G5	NC	-			PL11A	6	T	
H5	NC	-			PL11B	6	C	
F2	NC	-			PL12A	6	T	
F1	NC	-			PL12B	6	C	
H4	NC	-			PL13A	6	T	
H3	NC	-			PL13B	6	C	
G2	NC	-			PL14A	6	T	
-	-	-			GND6	6		
G1	NC	-			PL14B	6	C	
J4	NC	-			PL15A	6	T	LDQS15
J3	NC	-			PL15B	6	C	
J5	NC	-			PL16A	6	T	
K5	NC	-			PL16B	6	C	
H2	NC	-			PL17A	6	T	
H1	NC	-			PL17B	6	C	
J2	NC	-			PL18A	6	T	
-	-	-			GND6	6		
J1	NC	-			PL18B	6	C	
K4	TCK	6			TCK	6		
K3	TDI	6			TDI	6		
L3	TMS	6			TMS	6		
L5	TDO	6			TDO	6		
L4	VCCJ	6			VCCJ	6		

LFEC3 and LFECP/EC6 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFEC3				LFECP6/LFEC6			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
N16	PR14A	3	T	RLM0_PLLT_FB_A	PR23A	3	T	RLM0_PLLT_FB_A
N15	PR13B	3	C	RLM0_PLLC_IN_A	PR22B	3	C	RLM0_PLLC_IN_A
M15	PR13A	3	T	RLM0_PLLT_IN_A	PR22A	3	T	RLM0_PLLT_IN_A
M16	PR12B	3	C	DI/CSSPIN	PR21B	3	C	DI/CSSPIN
L16	PR12A	3	T	DOUT/CSON	PR21A	3	T	DOUT/CSON
K16	PR11B	3	C	BUSY/SISPI	PR20B	3	C	BUSY/SISPI
J16	PR11A	3	T	D7/SPID0	PR20A	3	T	D7/SPID0
L12	CFG2	3			CFG2	3		
L14	CFG1	3			CFG1	3		
L13	CFG0	3			CFG0	3		
K13	PROGRAMN	3			PROGRAMN	3		
L15	CCLK	3			CCLK	3		
K15	INITN	3			INITN	3		
K14	DONE	3			DONE	3		
	-	-			GND3	3		
H16	NC	-			PR18B	3	C	
H15	NC	-			PR18A	3	T	
G16	NC	-			PR17B	3	C	
G15	NC	-			PR17A	3	T	
K12	NC	-			PR16B	3	C	
J12	NC	-			PR16A	3	T	
J14	NC	-			PR15B	3	C	
J15	NC	-			PR15A	3	T	RDQS15
F16	NC	-			PR14B	3	C	
-	-	-			GND3	3		
F15	NC	-			PR14A	3	T	
J13	NC	-			PR13B	3	C	
H13	NC	-			PR13A	3	T	
H14	NC	-			PR12B	3	C	
G14	NC	-			PR12A	3	T	
E16	NC	-			PR11B	3	C	
E15	NC	-			PR11A	3	T	
H12	PR9B	2	C	PCLKC2_0	PR9B	2	C	PCLKC2_0
GND	GND2	2			GND2			
G12	PR9A	2	T	PCLKT2_0	PR9A	2	T	PCLKT2_0
G13	PR8B	2	C		PR8B	2	C	
F13	PR8A	2	T		PR8A	2	T	
F12	PR7B	2	C		PR7B	2	C	
E13	PR7A	2	T		PR7A	2	T	
D16	PR6B	2	C		PR6B	2	C	
D15	PR6A	2	T	RDQS6	PR6A	2	T	RDQS6
F14	PR5B	2	C		PR5B	2	C	
E14	PR5A	2	T		PR5A	2	T	

LFECP/EC20 and LFECP/EC33 Logic Signal Connections: 484 fpBGA (Cont.)

LFECP20/LFEC20					LFECP/LFEC33				
Ball Number	**Ball Function**	**Bank**	**LVDS**	**Dual Function**	**Ball Number**	**Ball Function**	**Bank**	**LVDS**	**Dual Function**
V2	PL41B	6	C	LLM0_PLLC_IN_A	V2	PL53B	6	C	LLM0_PLLC_IN_A
U3	PL42A	6	T	LLM0_PLLT_FB_A	U3	PL54A	6	T	LLM0_PLLT_FB_A
V3	PL42B	6	C	LLM0_PLLC_FB_A	V3	PL54B	6	C	LLM0_PLLC_FB_A
U4	PL43A	6	T		U4	PL55A	6	T	
V5	PL43B	6	C		V5	PL55B	6	C	
W1	PL44A	6	T		W1	PL56A	6	T	
GND	GND6	6			GND	GND6	6		
W2	PL44B	6	C		W2	PL56B	6	C	
Y1	PL45A	6	T	LDQS45	Y1	PL57A	6	T	LDQS57
Y2	PL45B	6	C		Y2	PL57B	6	C	
AA1	PL46A	6	T		AA1	PL58A	6	T	
AA2	PL46B	6	C		AA2	PL58B	6	C	
W4	PL47A	6	T		W4	PL59A	6	T	
V4	PL47B	6	C		V4	PL59B	6	C	
W3	PL48A	6	T	VREF1_6	W3	PL68A	6	T	VREF1_6
Y3	PL48B	6	C	VREF2_6	Y3	PL68B	6	C	VREF2_6
GND	GND6	6			GND	GND6	6		
GND	GND5	5			GND	GND6	6		
GND	-				GND	GND6	6		
GND	-				GND	GND5	5		
GND	GND5	5			GND	GND5	5		
V7	PB10A	5	T		V7	PB10A	5	T	
T6	PB10B	5	C		T6	PB10B	5	C	
V8	PB11A	5	T		V8	PB11A	5	T	
U7	PB11B	5	C		U7	PB11B	5	C	
W5	PB12A	5	T		W5	PB12A	5	T	
U6	PB12B	5	C		U6	PB12B	5	C	
AA3	PB13A	5	T		AA3	PB13A	5	T	
GND	GND5	5			GND	GND5	5		
AB3	PB13B	5	C		AB3	PB13B	5	C	
Y6	PB14A	5	T	BDQS14	Y6	PB14A	5	T	BDQS14
V6	PB14B	5	C		V6	PB14B	5	C	
AA5	PB15A	5	T		AA5	PB15A	5	T	
W6	PB15B	5	C		W6	PB15B	5	C	
Y5	PB16A	5	T		Y5	PB16A	5	T	
Y4	PB16B	5	C		Y4	PB16B	5	C	
AA4	PB17A	5	T		AA4	PB17A	5	T	
GND	GND5	5			GND	GND5	5		
AB4	PB17B	5	C		AB4	PB17B	5	C	
Y7	PB18A	5	T		Y7	PB18A	5	T	
W8	PB18B	5	C		W8	PB18B	5	C	
W7	PB19A	5	T		W7	PB19A	5	T	
U8	PB19B	5	C		U8	PB19B	5	C	
W9	PB20A	5	T		W9	PB20A	5	T	

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFEC20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
E24	NC	-			E24	PR8B	2	C	
D24	NC	-			D24	PR8A	2	T	
E22	NC	-			E22	PR7B	2	C	
F22	NC	-			F22	PR7A	2	T	
E21	NC	-			E21	PR6B	2	C	
D22	NC	-			D22	PR6A	2	T	RDQS6
E23	PR2B	2	C	VREF1_2	E23	PR2B	2	C	VREF1_2
D23	PR2A	2	T	VREF2_2	D23	PR2A	2	T	VREF2_2
GND	GND2	2			GND	GND2	2		
GND	GND1	1			GND	GND1	1		
G20	NC	-			G20	PT65B	1	C	
F20	NC	-			F20	PT65A	1	T	
D21	NC	-			D21	PT64B	1	C	
C21	NC	-			C21	PT64A	1	T	
C23	NC	-			C23	PT63B	1	C	
C22	NC	-			C22	PT63A	1	T	
B23	NC	-			B23	PT62B	1	C	
C24	NC	-			C24	PT62A	1	T	TDQS62
D20	NC	-			D20	PT61B	1	C	
-	-	-			GND	GND1	1		
E19	NC	-			E19	PT61A	1	T	
B25	NC	-			B25	PT60B	1	C	
B24	NC	-			B24	PT60A	1	T	
B26	NC	-			B26	PT59B	1	C	
A25	NC	-			A25	PT59A	1	T	
C20	NC	-			C20	PT58B	1	C	
C19	NC	-			C19	PT58A	1	T	
A24	PT57B	1	C		A24	PT57B	1	C	
-	-	-			GND	GND1	1		
A23	PT57A	1	T		A23	PT57A	1	T	
E18	PT56B	1	C		E18	PT56B	1	C	
D19	PT56A	1	T		D19	PT56A	1	T	
F19	PT55B	1	C		F19	PT55B	1	C	
B22	PT55A	1	T		B22	PT55A	1	T	
G19	PT54B	1	C		G19	PT54B	1	C	
B21	PT54A	1	T	TDQS54	B21	PT54A	1	T	TDQS54
D18	PT53B	1	C		D18	PT53B	1	C	
GND	GND1	1			GND	GND1	1		
C18	PT53A	1	T		C18	PT53A	1	T	
F18	PT52B	1	C		F18	PT52B	1	C	
A22	PT52A	1	T		A22	PT52A	1	T	
G18	PT51B	1	C		G18	PT51B	1	C	

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFEC20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
A21	PT51A	1	T		A21	PT51A	1	T	
E17	PT50B	1	C		E17	PT50B	1	C	
B17	PT50A	1	T		B17	PT50A	1	T	
C17	PT49B	1	C		C17	PT49B	1	C	
GND	GND1	1			GND	GND1	1		
D17	PT49A	1	T		D17	PT49A	1	T	
F17	PT48B	1	C		F17	PT48B	1	C	
E20	PT48A	1	T		E20	PT48A	1	T	
G17	PT47B	1	C		G17	PT47B	1	C	
B20	PT47A	1	T		B20	PT47A	1	T	
E16	PT46B	1	C		E16	PT46B	1	C	
A20	PT46A	1	T	TDQS46	A20	PT46A	1	T	TDQS46
A19	PT45B	1	C		A19	PT45B	1	C	
GND	GND1	1			GND	GND1	1		
B19	PT45A	1	T		B19	PT45A	1	T	
D16	PT44B	1	C		D16	PT44B	1	C	
C16	PT44A	1	T		C16	PT44A	1	T	
F16	PT43B	1	C		F16	PT43B	1	C	
A18	PT43A	1	T		A18	PT43A	1	T	
G16	PT42B	1	C		G16	PT42B	1	C	
B18	PT42A	1	T		B18	PT42A	1	T	
A17	PT41B	1	C		A17	PT41B	1	C	
GND	GND1	1			GND	GND1	1		
A16	PT41A	1	T		A16	PT41A	1	T	
D15	PT40B	1	C		D15	PT40B	1	C	
B16	PT40A	1	T		B16	PT40A	1	T	
E15	PT39B	1	C		E15	PT39B	1	C	
C15	PT39A	1	T		C15	PT39A	1	T	
F15	PT38B	1	C		F15	PT38B	1	C	
G15	PT38A	1	T	TDQS38	G15	PT38A	1	T	TDQS38
B15	PT37B	1	C		B15	PT37B	1	C	
GND	GND1	1			GND	GND1	1		
A15	PT37A	1	T		A15	PT37A	1	T	
E14	PT36B	1	C		E14	PT36B	1	C	
G14	PT36A	1	T		G14	PT36A	1	T	
D14	PT35B	1	C	VREF2_1	D14	PT35B	1	C	VREF2_1
E13	PT35A	1	T	VREF1_1	E13	PT35A	1	T	VREF1_1
F14	PT34B	1	C		F14	PT34B	1	C	
C14	PT34A	1	T		C14	PT34A	1	T	
B14	PT33B	0	C	PCLKC0_0	B14	PT33B	0	C	PCLKC0_0
GND	GND0	0			GND	GND0	0		
A14	PT33A	0	T	PCLKT0_0	A14	PT33A	0	T	PCLKT0_0

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFEC20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
H7	VCCAUX	-			H7	VCCAUX	-		
J19	VCCAUX	-			J19	VCCAUX	-		
J8	VCCAUX	-			J8	VCCAUX	-		
K7	VCCAUX	-			K7	VCCAUX	-		
L20	VCCAUX	-			L20	VCCAUX	-		
M20	VCCAUX	-			M20	VCCAUX	-		
M7	VCCAUX	-			M7	VCCAUX	-		
N20	VCCAUX	-			N20	VCCAUX	-		
P20	VCCAUX	-			P20	VCCAUX	-		
P7	VCCAUX	-			P7	VCCAUX	-		
T20	VCCAUX	-			T20	VCCAUX	-		
T7	VCCAUX	-			T7	VCCAUX	-		
T8	VCCAUX	-			T8	VCCAUX	-		
V19	VCCAUX	-			V19	VCCAUX	-		
V7	VCCAUX	-			V7	VCCAUX	-		
W20	VCCAUX	-			W20	VCCAUX	-		
Y13	VCCAUX	-			Y13	VCCAUX	-		
Y7	VCCAUX	-			Y7	VCCAUX	-		
K19	VCC[1]	-			K19	VCCPLL	-		
L8	VCC[1]	-			L8	VCCPLL	-		
U19	VCC[1]	-			U19	VCCPLL	-		
U8	VCC[1]	-			U8	VCCPLL	-		

1. Tied to V_{CCPLL}.

LatticeEC Industrial (Continued)

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC15E-3F484I	352	-3	fpBGA	484	IND	15.3K
LFEC15E-4F484I	352	-4	fpBGA	484	IND	15.3K
LFEC15E-3F256I	195	-3	fpBGA	256	IND	15.3K
LFEC15E-4F256I	195	-4	fpBGA	256	IND	15.3K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC20E-3F672I	400	-3	fpBGA	672	IND	19.7K
LFEC20E-4F672I	400	-4	fpBGA	672	IND	19.7K
LFEC20E-3F484I	360	-3	fpBGA	484	IND	19.7K
LFEC20E-4F484I	360	-4	fpBGA	484	IND	19.7K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC33E-3F672I	496	-3	fpBGA	672	IND	32.8
LFEC33E-4F672I	496	-4	fpBGA	672	IND	32.8
LFEC33E-3F484I	360	-3	fpBGA	484	IND	32.8
LFEC33E-4F484I	360	-4	fpBGA	484	IND	32.8

LatticeECP Industrial

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP6E-3F484I	224	-3	fpBGA	484	IND	6.1K
LFECP6E-4F484I	224	-4	fpBGA	484	IND	6.1K
LFECP6E-3F256I	195	-3	fpBGA	256	IND	6.1K
LFECP6E-4F256I	195	-4	fpBGA	256	IND	6.1K
LFECP6E-3Q208I	147	-3	PQFP	208	IND	6.1K
LFECP6E-4Q208I	147	-4	PQFP	208	IND	6.1K
LFECP6E-3T144I	97	-3	TQFP	144	IND	6.1K
LFECP6E-4T144I	97	-4	TQFP	144	IND	6.1K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP10E-3F484I	288	-3	fpBGA	484	IND	10.2K
LFECP10E-4F484I	288	-4	fpBGA	484	IND	10.2K
LFECP10E-3F256I	195	-3	fpBGA	256	IND	10.2K
LFECP10E-4F256I	195	-4	fpBGA	256	IND	10.2K
LFECP10E-3Q208I	147	-3	PQFP	208	IND	10.2K
LFECP10E-4Q208I	147	-4	PQFP	208	IND	10.2K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP15E-3F484I	352	-3	fpBGA	484	IND	15.3K
LFECP15E-4F484I	352	-4	fpBGA	484	IND	15.3K
LFECP15E-3F256I	195	-3	fpBGA	256	IND	15.3K
LFECP15E-4F256I	195	-4	fpBGA	256	IND	15.3K

LatticeECP Industrial (Continued)

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP20E-3F672I	400	-3	fpBGA	672	IND	19.7K
LFECP20E-4F672I	400	-4	fpBGA	672	IND	19.7K
LFECP20E-3F484I	360	-3	fpBGA	484	IND	19.7K
LFECP20E-4F484I	360	-4	fpBGA	484	IND	19.7K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP33E-3F672I	496	-3	fpBGA	672	IND	32.8K
LFECP33E-4F672I	496	-4	fpBGA	672	IND	32.8K
LFECP33E-3F484I	360	-3	fpBGA	484	IND	32.8K
LFECP33E-4F484I	360	-4	fpBGA	484	IND	32.8K

LatticeEC Industrial (Continued)

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC15E-3FN484I	352	-3	Lead-Free fpBGA	484	IND	15.3K
LFEC15E-4FN484I	352	-4	Lead-Free fpBGA	484	IND	15.3K
LFEC15E-3FN256I	195	-3	Lead-Free fpBGA	256	IND	15.3K
LFEC15E-4FN256I	195	-4	Lead-Free fpBGA	256	IND	15.3K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC20E-3FN672I	400	-3	Lead-Free fpBGA	672	IND	19.7K
LFEC20E-4FN672I	400	-4	Lead-Free fpBGA	672	IND	19.7K
LFEC20E-3FN484I	400	-3	Lead-Free fpBGA	484	IND	19.7K
LFEC20E-4FN484I	400	-4	Lead-Free fpBGA	484	IND	19.7K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC33E-3FN672I	496	-3	Lead-Free fpBGA	672	IND	32.8K
LFEC33E-4FN672I	496	-4	Lead-Free fpBGA	672	IND	32.8K
LFEC33E-3FN484I	360	-3	Lead-Free fpBGA	484	IND	32.8K
LFEC33E-4FN484I	360	-4	Lead-Free fpBGA	484	IND	32.8K

LatticeECP Industrial

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFECP6E-3FN484I	224	-3	Lead-Free fpBGA	484	IND	6.1K
LFECP6E-4FN484I	224	-4	Lead-Free fpBGA	484	IND	6.1K
LFECP6E-3FN256I	195	-3	Lead-Free fpBGA	256	IND	6.1K
LFECP6E-4FN256I	195	-4	Lead-Free fpBGA	256	IND	6.1K
LFECP6E-3QN208I	147	-3	Lead-Free PQFP	208	IND	6.1K
LFECP6E-4QN208I	147	-4	Lead-Free PQFP	208	IND	6.1K
LFECP6E-3TN144I	97	-3	Lead-Free TQFP	144	IND	6.1K
LFECP6E-4TN144I	97	-4	Lead-Free TQFP	144	IND	6.1K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFECP10E-3FN484I	288	-3	Lead-Free fpBGA	484	IND	10.2K
LFECP10E-4FN484I	288	-4	Lead-Free fpBGA	484	IND	10.2K
LFECP10E-3FN256I	195	-3	Lead-Free fpBGA	256	IND	10.2K
LFECP10E-4FN256I	195	-4	Lead-Free fpBGA	256	IND	10.2K
LFECP10E-3QN208I	147	-3	Lead-Free PQFP	208	IND	10.2K
LFECP10E-4QN208I	147	-4	Lead-Free PQFP	208	IND	10.2K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFECP15E-3FN484I	352	-3	Lead-Free fpBGA	484	IND	15.3K
LFECP15E-4FN484I	352	-4	Lead-Free fpBGA	484	IND	15.3K
LFECP15E-3FN256I	195	-3	Lead-Free fpBGA	256	IND	15.3K
LFECP15E-4FN256I	195	-4	Lead-Free fpBGA	256	IND	15.3K

LatticeECP/EC Family Data Sheet Supplemental Information

September 2012 **Data Sheet**

For Further Information

A variety of technical notes for the LatticeECP/EC family are available on the Lattice web site at www.latticesemi.com.

- LatticeECP/EC sysIO Usage Guide (TN1056)
- LatticeECP/EC sysCLOCK PLL Design and Usage Guide (TN1049)
- Memory Usage Guide for LatticeECP/EC Devices (TN1051)
- LatticeECP/EC DDR Usage Guide (TN1050)
- Power Estimation and Management for LatticeECP/EC and LatticeXP Devices (TN1052)
- LatticeECP-DSP sysDSP Usage Guide (TN1057)
- LatticeECP/EC sysCONFIG Usage Guide (TN1053)
- IEEE 1149.1 Boundary Scan Testability in Lattice Devices

For further information about interface standards refer to the following web sites:

- JEDEC Standards (LVTTL, LVCMOS, SSTL, HSTL): www.jedec.org
- PCI: ww.pcisig.com